

WCNLB8-SD11

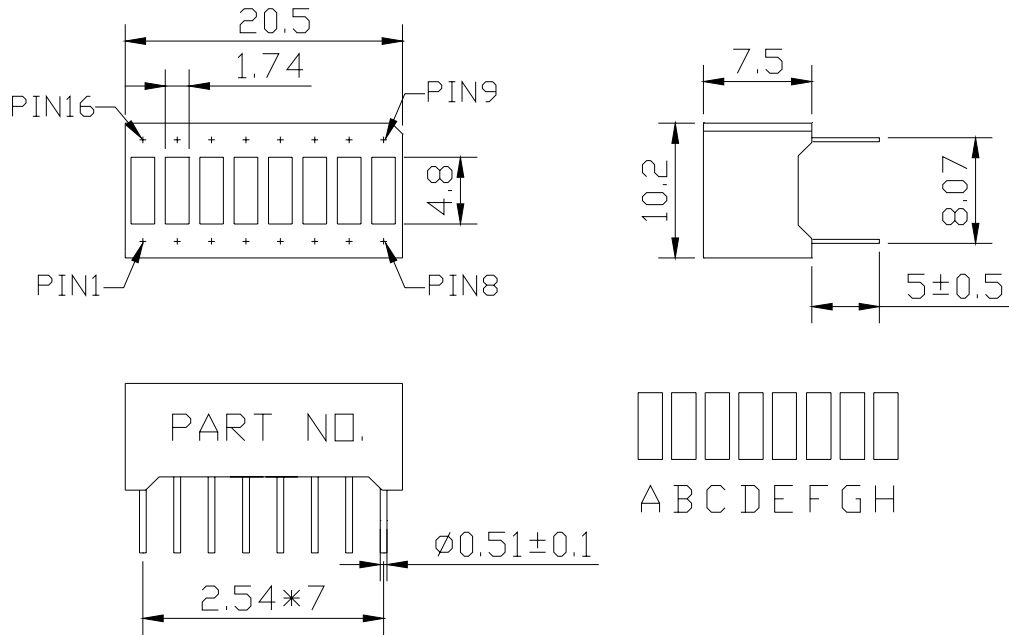
SPECIFICATION

WCN			CUSTOMER Confirmed
Prepared by	Checked by	Approved by	
Fei 2016-8-4	Athena	William	
REVISION RECORD			



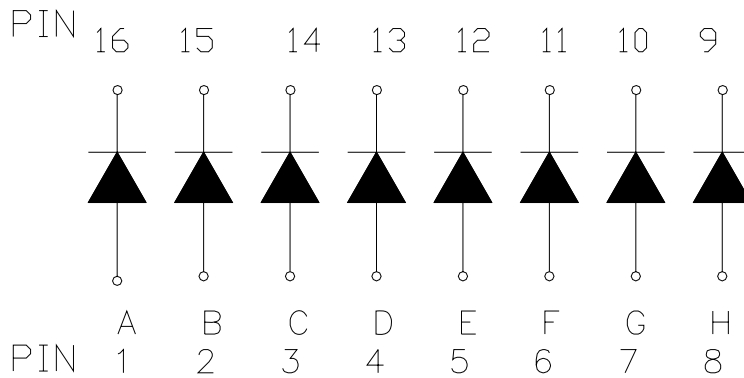
REVISION: A0

■ Outer Dimension:



Notes: Unless otherwise stated, The tolerance is $\pm 0.25\text{mm}$.

■ Circuit Diagram:



■ Pin Connection:

PIN NO.	CONNECTION	PIN NO.	CONNECTION	PIN NO.	CONNECTION
1	Anode A	7	Anode G	13	Cathode D
2	Anode B	8	Anode H	14	Cathode C
3	Anode C	9	Cathode H	15	Cathode B
4	Anode D	10	Cathode G	16	Cathode A
5	Anode E	11	Cathode F	/	/
6	Anode F	12	Cathode E	/	/

■ **Features:**

- High Reliability
- Color: Super Red
- Low Power Requirement
- Easy Assembly

■ **Description:**

- Eight Windows Display
- Digit Height 4.80mm(0.19") and Width 1.74mm(0.07")
- Black Face and Milky Bar

■ **Absolute Maximum Rating (Ta=25°C):**

Parameter	Symbol	Condition	Color	Rating	Units
Power Dissipation Per Bar	P _d	—	Red	62.5	mW
Forward Current Per Bar	I _F	—	Red	25	mA
Peak Forward Current Per Bar	I _{FP}	1/10 Duty 10KHz	Red	100	mA
Reverse Voltage Per Bar	V _R	—	Red	5	V
Operating Temperature Range	Topr	—	—	-35~+85	°C
Storage Temperature Range	Tstg	—	—	-35~+85	°C

■ **Electrical/Optical Characteristics Rating(Ta=25°C)**

Item	Symbol	Test conditions	Location	Rating			Units
				Min.	Typ.	Max.	
Forward Voltage	V _F	I _F =20mA	Per Bar	—	2.00	2.50	V
Reverse Current	I _R	V _R =5V	Per Bar	—	—	100	μA
Luminous Intensity	I _V	I _F =10mA	Per Bar	7201	11500	18000	μcd
Wave Length	λ _P	I _F =20mA	Per Bar	—	660	—	nm
	λ _D				640		
Spectral Line Half Width	△λ	I _F =20mA	Per Bar	—	30	—	nm
Luminous Intensity Matching Ratio (Bar to Bar)	I _{v-m}	I _F =10mA				1.2:1	

■ **Luminous Intensity Sorting: (Luminous Intensity Tolerance is +/-10%)**

Rank	Symbol	Condition	Min	Max	Unit
O	O	I _F =10mA	7201	8500	μcd
P	P	I _F =10mA	8501	10500	μcd
Q	Q	I _F =10mA	10501	12800	μcd
R	R	I _F =10mA	12801	15250	μcd
S	S	I _F =10mA	15251	18000	μcd

■ **Soldering Conditions: Soldering Temp. ≤ +260°C Soldering Time. ≤ 3sec.**
 (at 2mm Distance from The Case of Reflector Edge).

■ **Typical Elector-Optical Characteristics Curve:**

Fig1. Forward Current vs. Forward Voltage:

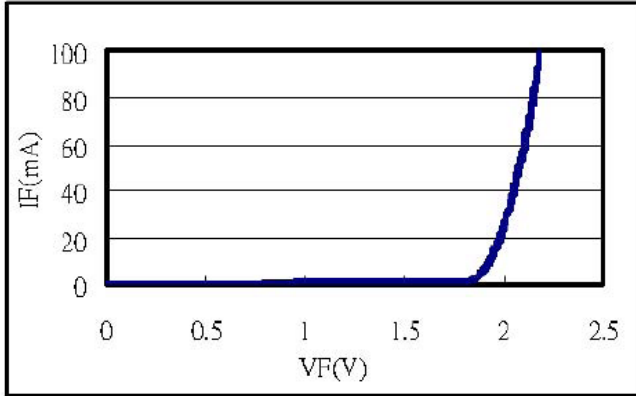


Fig2. Forward Current vs. Relative Intensity:

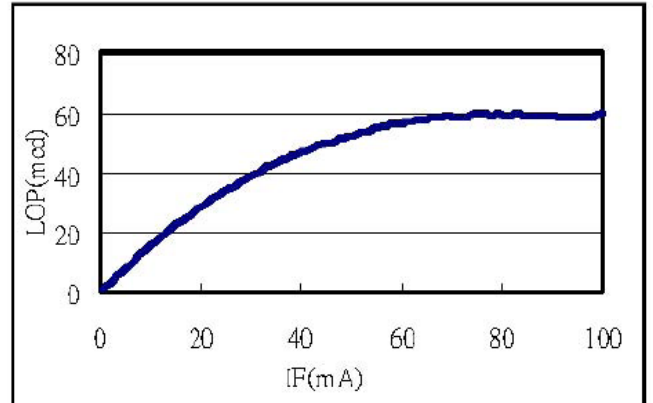


Fig3. Forward Current vs. Relative Wavelength:

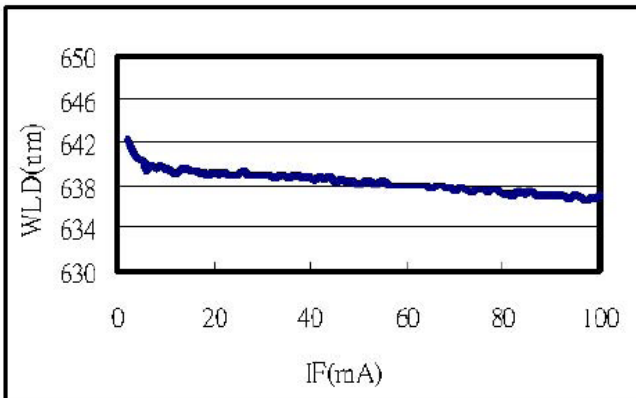


Fig4. Temperature vs. Relative Intensity:

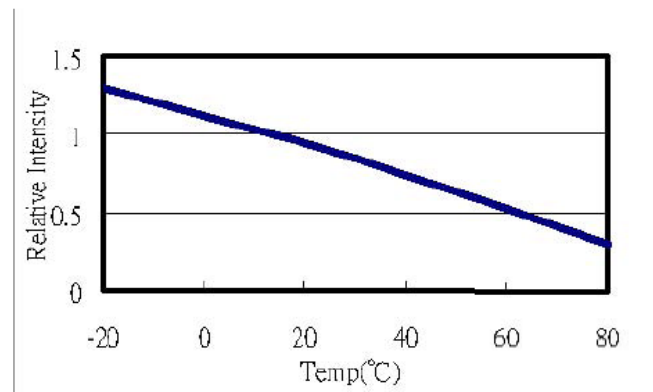


Fig5. Temperature vs. Relative Wavelength:

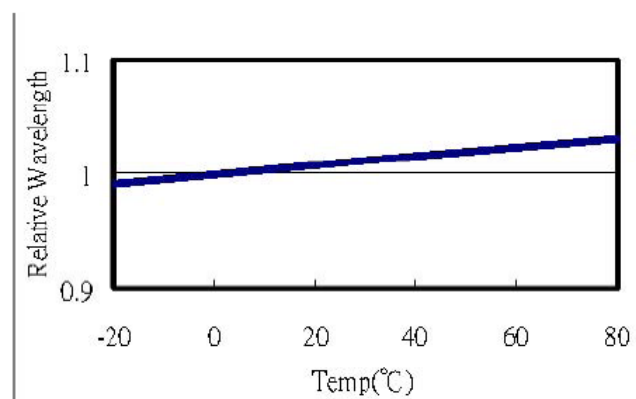
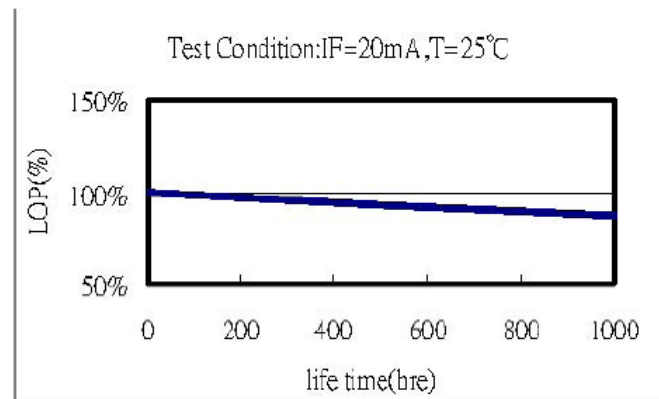


Fig6. Life Test at 20mA R.T. 1000hrs:



■ LED Displays Reliability Test:

CLASSIFICATION	TEST ITEM	DESCRIPTION AND TEST CONDITION
ENDURANCE TEST	OPERATION LIFE	EVALUATES RESISTANCE OF THE DEVICE WHEN OPERATED AT ELECTRICAL STRESS T _a = UNDER ROOM TEMPERATURE I _F = I _F max
	HIGH TEMPERATURE HIGH HUMIDITY STORAGE	EVALUATES MOISTURE RESISTANCE OF THE DEVICE WHEN STORED FOR A LONG TERM AT HIGH TEMPERATURE AND HUMIDITY T _a = 65±5°C RH=90~95%RH TEST TIME=240± 2Hrs
	HIGH TEMPERATURE STORAGE	EVALUATES DEVICE DURABILITY FOR LONG TERM STORAGE IN HIGH TEMPERATURE T _a = 85±5°C(COB: T _a =65±5°C) TEST TIME=1000Hrs(-24Hrs, +72Hrs)
	LOW TEMPERATURE STORAGE	EVALUATES DEVICE DURABILITY FOR LONG TERM STORAGE IN LOW TEMPERATURE T _a = -35±5°C TEST TIME=1000Hrs(-24Hrs, +72Hrs)
ENVIRONMENTAL TEST	TEMPERATURE CYCLING	EVALUATES RESISTANCE OF DEVICE AT THERMAL STRESSES OR EXPANSION AND CONTRACTION 85°C ~ 25°C ~ -35°C ~ 25°C 30min 5min 30min 5min 10 CYCLES(COB: T _{hot} =65°C, T _{cold} =-25°C)
	THERMAL SHOCK	EVALUATES DEVICE STRUCTURE AND STRUCTURE AND MECHANICAL RESISTANCE WHEN SUDDENLY EXPOSED AT SERVE CHANGES 85±5°C ~ -35±5°C 10min 10min 10 CYCLES(COB: T _{hot} =65°C, T _{cold} =-25°C)
	SOLDERABILITY	EVALUATES SOLDERABILITY ON LEADS OF DEVICE T.SOL=230±5°C DWELL TIME=5±1sec.
	SOLDER RESISTANCE	EVALUATES RESISTANCE TO THERMAL STRESS CAUSED BY SOLDERING T.SOL=260±5°C DWELL TIME=10±1sec.

■ Packing method A:

224pcs / Red Expandable Polyethylene.

1340 pcs / Box(360*175*130mm).

8040 pcs / Catton(550*380*280mm).

■ Packing method B:

25 pcs / IC Tube.

1925 pcs / Box(537*175*125mm).

7700 pcs / Catton(550*380*280mm).